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HEAT SINK HAVING AN ASSEMBLING DEVICE

ABSTRACT

5 A heat sink having an assembling device using
mechanical characteristics of resilience or flexibility
so as to ~~obtain the effectiveness of fastening~~ ¹⁶ a heat
sink. In ^{one} ~~an~~ embodiment, this invention comprises a
chassis having a heat dissipating surface, a plurality
of fastening holes formed on the chassis, and fastening
bolts and helical springs corresponding to the
10 fastening holes, wherein the fastening bolts each
further comprise a ^{mushroom} ~~fungus~~-shaped insertion end. In
another embodiment, the heat sink comprises a chassis
having a heat dissipating surface and a fastening seat
for fastening the heat sink, wherein the fastening seat
15 is formed of a resiliently curvable and integrally
formed sheet and is provided with a pair of hooks each
having a V-shaped barb for inserting the invention into
holes abutting the chip and pre-formed on a motherboard
and for resiliently pressing the heat sink against the
20 chip.

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